Ref #	Hits	Search Query	DBs	Default Operat or	Plural s	Time Stamp
L1	195073	(trench groove hole via opening recess damascene) with (insulat\$ dielectric)	US-PGPU B; USPAT	OR	ON	2005/11/30 17:56
L2	101823	1 and (trench groove hole via opening recess damascene insulat\$ dielectric) with substrate	US-PGPU B; USPAT	OR	ON	2005/11/30 17:12
L3	66197	2 and (trench groove hole via opening recess damascene insulat\$ dielectric) with etch\$3	US-PGPU B; USPAT	OR	ON	2005/11/30 17:12
L4	19026	3 and (etch\$3 with plasma)	US-PGPU B; USPAT	OR	ON	2005/11/30 17:13
L5	2635	4 and (etch\$3 with (hydrogen h2))	US-PGPU B; USPAT	OR	ON .	2005/11/30: 17:55
L6	578	5 and (etch\$3 with (chlorine))	US-PGPU B; USPAT	OR	ON	2005/11/30 17:56
L7	99	6 and (trench groove hole via opening recess damascene) with (silicide)	US-PGPU B; USPAT	OR	ON	2005/11/30 17:17
L8	97	7 and (trench groove hole via opening recess damascene silicide) with contact	US-PGPU B; USPAT	OR	ON	2005/11/30 17:21
L9	97	7 and (trench groove hole via opening recess damascene silicide) near5 contact	US-PGPU B; USPAT	OR	ON	2005/11/30 17:23
L10	79	"5811022"	US-PGPU B; USPAT	OR	ON	2005/11/30 17:21
L11	69	("5811022").URPN.	USPAT	OR	ON	2005/11/30 17:22

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L12	107	("2981902"   "3054742"	US-PGPU	OR	ON	2005/11/30
1		"3109801"   "3278384"	B;			17:22
		"3343022"   "3433705"	USPAT;			
		"3500118"   "3509500"	USOCR			
		"3663361"   "3794941"				
		"3906405"   "3987334"				·
		"4057462"   "4073680"				
		"4088926"   "4095198"				
		"4110595"   "4180763"				,
	:	"4201960"   "4252609"				
		"4263096"   "4282267"				
		"4292125"   "4368092"				
		"4431898"   "4431901"			·	
		"4486722"   "4486723"				
		"4601871"   "4626400"	+			
		"4679007"   "4689192"				
		"4732761"   "4735765"				
		"4748383"   "4767590"				
		"4780803"   "4786352"				
1		"4794217"   "4859399"				
		"4861622"   "4863671"				,
		"4877757"   "4878149"				
		"4908492"   "4918031"				
		"4985113"   "4996077"				
		"5030889"   "5061838"				
		"5130003"   "5153484"				
		"5187454"   "5200595"				
		"5254830"   "5277751"				
		"5290382"   "5303139"				
		"5336355"   "5346578"				
		"5364600"   "5401350"	İ			
		"5405480"   "5406177"	•			
		"5414238"   "5430355"				,
		"5440206"   "5458732"				
		"5460689"   "5468296"				
	İ	"5472561"   "5474648"				
		"5479072"   "5505780"				
		"5506507"   "5514246"				
		"5556549"   "5565247"				
		"5573595"   "5576629"				
		"5618382"   "5630880"				
	;	"5643364"   "5654679"				
		"5670881"   "5712592"				
		"5747935"   "5756400"				
		"5773919"   "5811022"				
		"5939886"   "5998933"				
		"6007879"   "6164241"				
		"6253704"   "6424232"				
		"6459066"   "H000268"				
		"H000554").PN. OR				
		("6924455").URPN.				
Search Hi	story 11/30/0:	5 6:34:36 PM Page 2	1			

L13	0	4 and (etch\$3 with (hydrogen h2)) with contac adj hole	US-PGPU B; USPAT	OR	ON	2005/11/30 17:55
L14	107	4 and (etch\$3 with (hydrogen h2)) with contact adj hole	US-PGPU B; USPAT	OR	ON	2005/11/30 17:55
L15	22	14 and (etch\$3 with (chlorine))	US-PGPU B; USPAT	OR	ON	2005/11/30 17:56
L16	3	15 and (trench groove hole via opening recess damascene) with (silicide)	US-PGPU B; USPAT	OR	ON	2005/11/30 18:07
L17	1	2002/0074312	US-PGPU B; USPAT	OR	ON	2005/11/30 18:09
L18	1	"20020074312"	US-PGPU B; USPAT	OR	ON	2005/11/30 18:11
L19	8	"5320708"	US-PGPU B; USPAT	OR	ON	2005/11/30 18:15
L20	14	"5900288"	US-PGPU B; USPAT	OR	ON	2005/11/30. 18:17
L21	10394	(conduct\$ adj contact withinsulat\$3 with substrate with opening with first adj plasma and second adj plasma with silicide).clm.	US-PGPU B; USPAT	OR	ON	2005/11/30 18:18
L22	0	(conduct\$ adj contact with insulat\$3 with substrate with opening with first adj plasma and second adj plasma with silicide).clm.	US-PGPU B; USPAT	OR	ON	2005/11/30 18:19
L23	0	(conduct\$ adj contact with insulat\$3 with substrate with opening with first adj plasma and second adj plasma with silicide).clm.	US-PGPU B; USPAT; USOCR; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2005/11/30 18:20

Ref #	Hits	Search Query	DBs	Default Operat or	Plural s	Time Stamp
L23	0	(conduct\$ adj contact with insulat\$3 with substrate with opening with first adj plasma and second adj plasma with silicide).clm.	US-PGPU B; USPAT; USOCR; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2005/11/30 18:20